



DOCUMENT CHANGE REQUEST

DCR number 1062

Changes required for: Proc

Originator: Jean-Paul Bussenot

Date: 2017/12/04

Date sent: 2016/12/13

Organisation: CNES

Status: IMPLEMENTED

Title: DESTRUCTIVE PHYSICAL ANALYSIS OF EEE COMPONENTS

Number: 21001

Issue: 1

Other documents affected:

Page:

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Paragraph:

Appendices A1.1 and A1.2

Original wording:

NOTES:

A1.1 - The dielectric thickness shall be verified to be a minimum of 20m.

A1.2 - The dielectric thickness shall be verified to be a minimum of 0.2mm (ref. JPL-D-20348).

Proposed wording:

Remove note from both appendices

Justification:

On ESCC parts submitted to evaluation, technological limits are based on evaluation results.

For chips, the three ESCC qualified manufacturers have products with fired dielectric thicknesses below 20µm.

Attachments:

N/A

Modifications:

N/A

Approval signature:

Date signed:

2017-12-04